

EtraLED

EtraLED-LG-8520 LG Innotek Modular Passive Star Heat Sink Φ 85mm

Features VS Benefits

- * The EtraLED-LG-8520 LG Innotek Modular Passive Star LED Heat Sinks are specifically designed for luminaires using the LG Innotek LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 1200 to 3,100 lumen.
- * Thermal resistance range R_{th} 2.38°C/W.
- * Modular design with mounting holes foreseen for direct mounting of LG Innotek COB series.
- * Diameter 85.0mm - standard height 20.0mm Other heights on request.
- * Forged from highly conductive aluminum.



Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of LG Innotek COB's and LED modules which standard fit on the star LED heat sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of star LED heat sinks.



LG Innotek LED Modules directly Mounting Options

LG Innotek 7W&10W COB series.

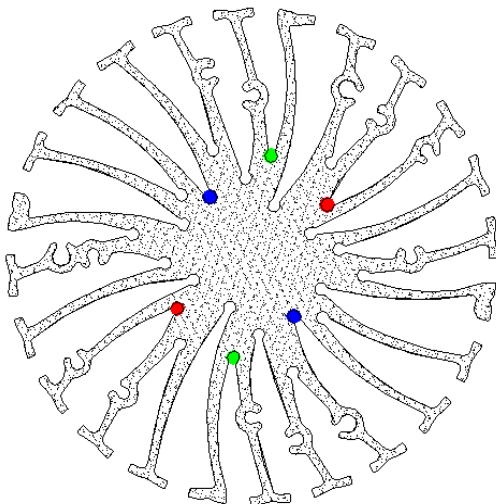
- LEMWM19480xxxxxx;
- LEMWM19490xxxxxx;
- LEMWM19680xxxxxx;
- LEMWM19690xxxxxx;

With the Zhaga Book 3 holders for the green indicator marks.
TE Connectivity Holder: 2213382-1;
Without the holders for the blue indicator marks.
Direct mounting with machine screws M3x6.5mm.

LG Innotek 16W&21W COB series.

- LEMWM24780xxxxxx;
- LEMWM24790xxxxxx;
- LEMWM24980xxxxxx;
- LEMWM24990xxxxxx;

With the Zhaga Book 3 holders for the green indicator marks.
TE Connectivity Holder: 2213130-1;
BJB Holder: 47.319.2011.50;
Without the holders for the red indicator marks.
Direct mounting with machine screws M3x6.5mm.



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Mounting Options and Drawings & Dimensions

Example: EtraLED-LG-8520-B-1,2

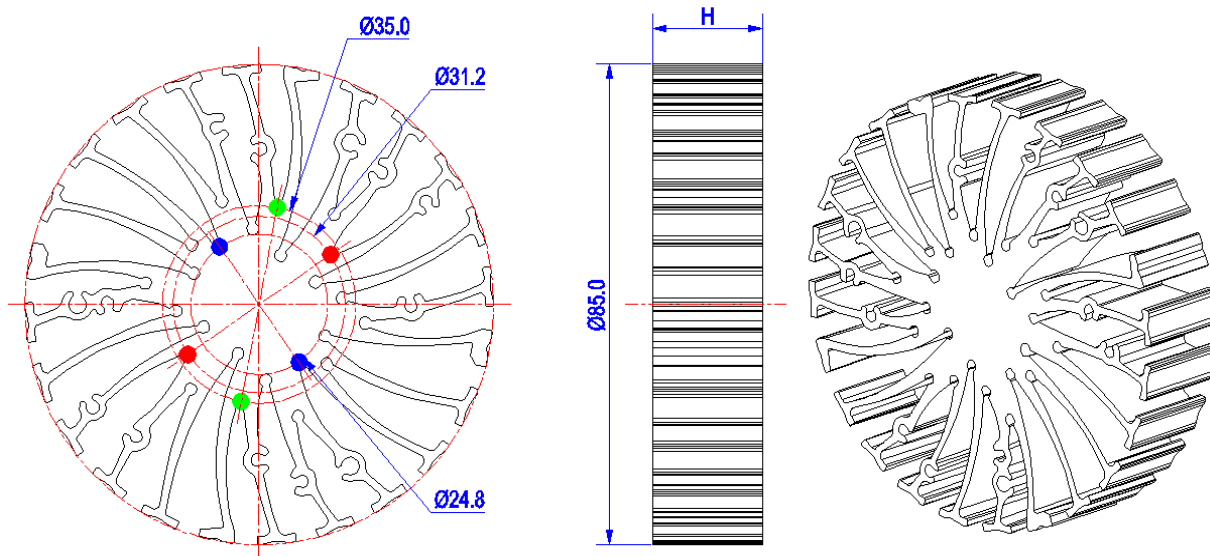
Example: EtraLED-LG-85 **1** - **2** - **3**

- 1** Height (mm)
- 2** Anodising Color
B-Black
C-Clear
Z-Custom
- 3** Mounting Options - see graphics for details Combinations available
Ex.order code - 12
means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
1	7W&10W COB	/	M3	6.5mm	24.8mm/ 2-@180°
2		/	M3	6.5mm	31.2mm/ 2-@180°
3	16W&21W COB	BJB Holder 47.319.2011.50	M3	6.5mm	35.0mm/ 2-@180° (Zhaga Book 3)
	7W&10W COB	TE Holder 2213382-1			



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The product data table

	Model No.	EtraLED-LG-8520
	Heatsink Size	Φ85xH20mm
	Heatsink Material	AL6063-T5
	Finish	Black Anodized
	Weight (g)	115.0
	Dissipated power (T_{hs-amb},50°C)	21.0 (W)
	Cooling surface area (mm²)	40076
	Thermal Resistance (R_{hs-amb})	2.38 (°C/W)

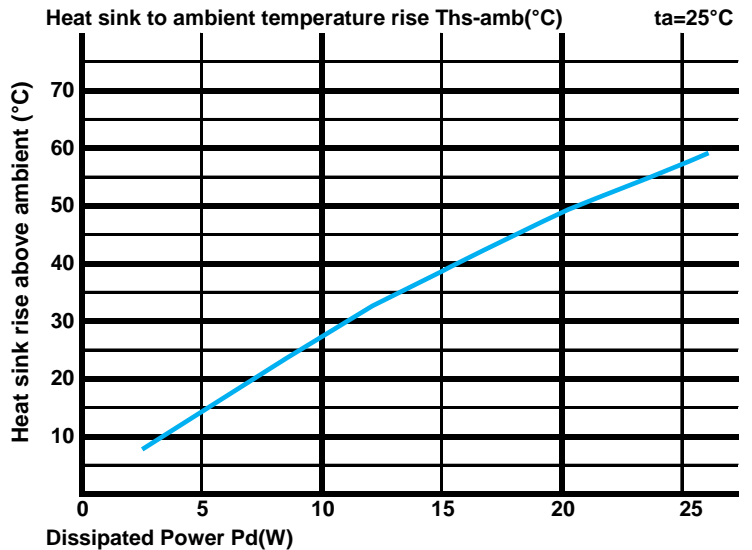
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light efficiency of the LED module;

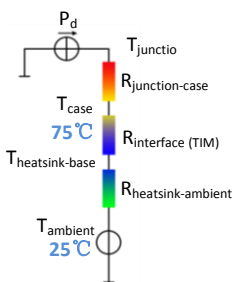
Dissipated Power Pd(W)	Pd = Pe x (1-ηL)	Heat sink to ambient thermal resistance R _{hs-amb} (°C/W)	Heat sink to ambient temperature rise T _{hs-amb} (°C)
		EtraLED-LG-8520	
5.0		2.80	14.0
10.0		2.70	27.0
15.0		2.53	38.0
20.0		2.40	48.0
25.0		2.28	57.0



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (T_{hs} - T_a) / P_d$

θ - Thermal Resistance [°C/W]; T_{hs} - Heatsink temperature ; T_a - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface (TIM)}$ [°C/W], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].

*Thermal resistances outside the package $R_{interface (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used:

$$T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot P_d + T_{ambient}$$